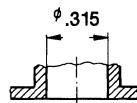


# Silicon Power Rectifiers

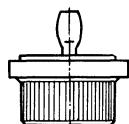
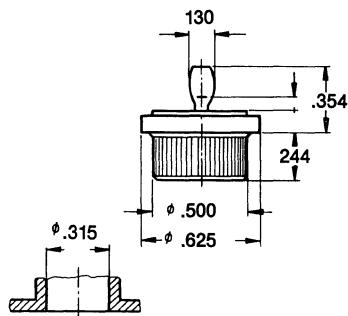
Press-fit diode for 1100 V and 1500 V; 35 A

# Series SSIE43, SSIE44

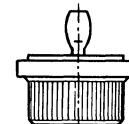
- Copper case press fit, knurled and tin-plated
- Designed for high thermal fatigue applications
- Polarity: Case = cathode, red stamp (SSIE43)  
Case = anode, black stamp (SSIE44)



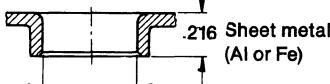
Insertion tool



Diode

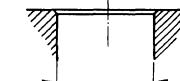


Diode mounting



.216  
 $\phi .4961 + .0020 - .0004$

Sheet metal  
(Al or Fe)



Sealed body  
(Al or Cu)

$\phi .4961 + .0020 - .0004$

Type	Ordering Code	Repetitive peak reverse voltage $V_{RRM}$	Surge peak reverse voltage $V_{RRM}$
SSIE4360	C66047-A1066-A4	1100V	1100V
SSIE4383	C66047-A1066-A5	1500V	1500V
SSIE4460	C66047-A1066-A9	1100V	1100V
SSIE4483	C66047-A1066-A10	1500V	1500V

**Electrical Characteristics****Forward Conducting**

Max. RMS current	$I_F$ (RMS)	55 Amps	$T_C = 120^\circ\text{C}$
Max. average current	$I_F$ (AVG)	35 Amps	$T_C = 120^\circ\text{C}$ , half sine
Max. peak voltage	$V_{FM}$	1.2 Volts	$I_{FM} = 50 \text{ Amps}$
Max. peak 1 cycle surge current	$I_{FSM}$	300 Amps	$T_J = 175^\circ\text{C}, 60\text{Hz}$
Max. $I^2t$ for fusing	$I^2t$	340 A <sup>2</sup> sec	$T_J = 175^\circ\text{C}, t = 8.3 \text{ ms}$

**Thermal Values**

Max. DC thermal resistance, junction to case	$R_{\Theta JC}$	1.0C/W
Operating junction temp. range	$T_J$	-40°C to +175°C
Storage temperature range	$T_{stg}$	-40°C to +175°C

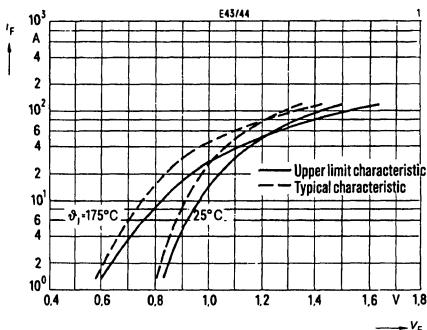
**Blocking**

Max. reverse leaking current	$I_{RRM}$	4 mA	$T_J = 175^\circ\text{C}, V_R = V_{RRM}$
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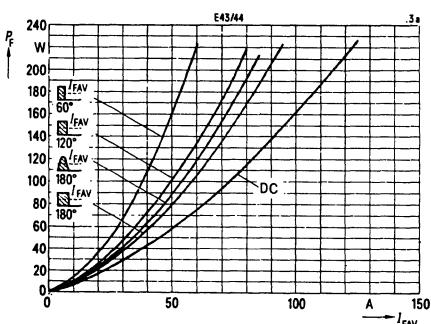
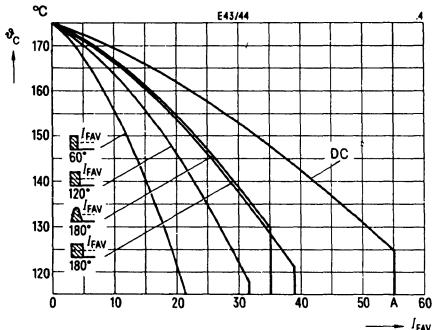
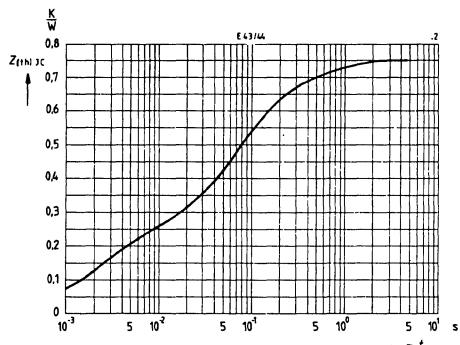
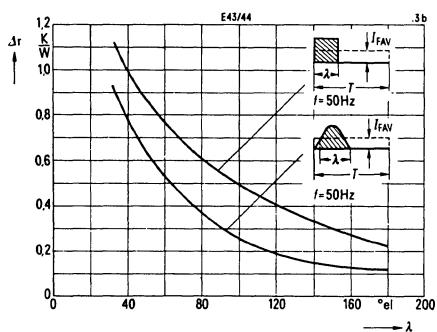
**Mechanical Characteristics**

Max. press-in force	867 lb
Weight	Approximately 0.35 ounces (10 grams)

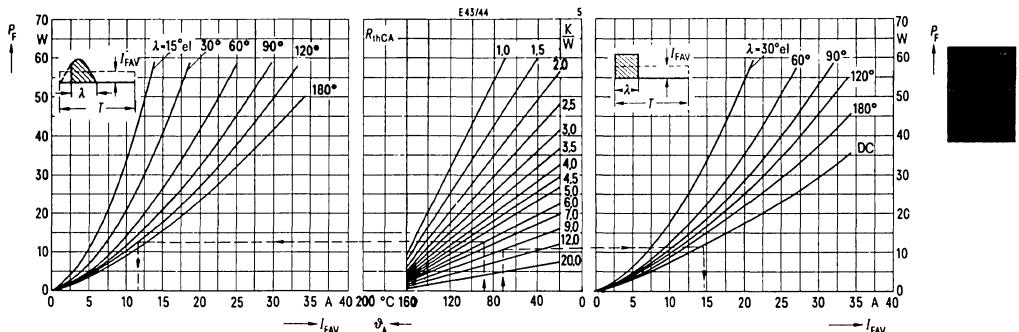
(1)  $T_C = 25^\circ\text{C}$  unless otherwise indicated

**Forward characteristic curves**Parameter: junction temperature  $\vartheta_j$ **Forward power dissipation characteristic curves**

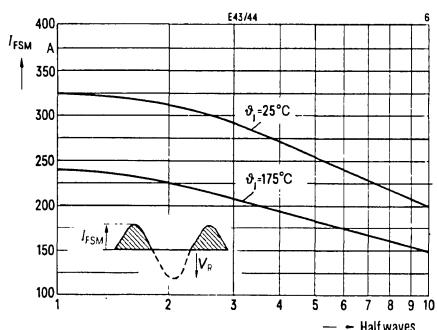
Parameter: current waveform

**Permissible case temperature  $\vartheta_c$  versus forward current, mains operation 40 to 60 Hz****Transient thermal resistance**for constant current  $Z_{(th)JC}$ **Thermal resistance  $\Delta r$** Parameters: frequency  $f$ , current waveform

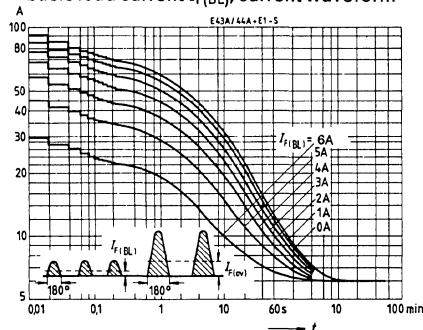
**Forward power dissipation characteristic curves,**  
nomogram for determining max. mean forward currents (limit value)  
for various cooling conditions, mains operation 40 to 1000 Hz



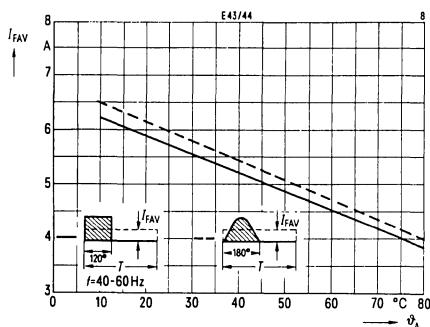
**Maximum current characteristic curves**  
Parameter: junction temperature  $\theta_j$   
 $V_R \leq 0.8 V_{RRM}$



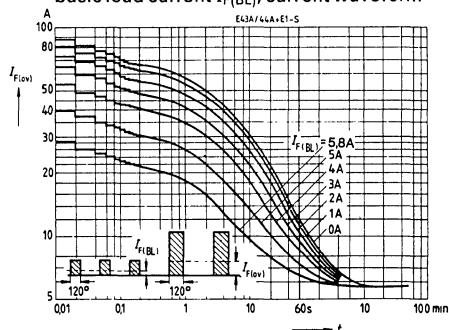
**Overcurrent characteristic curves (mean value)**  
for heat sink E1, cooling type (S),  $\theta_A = 45^\circ\text{C}$ ,  
mains operation 40 to 60 Hz. Parameters:  
basic load current  $I_{F(BL)}$ , current waveform



**Max. mean forward current  $I_{FAV(II)}$  for heat sink E1 and mounting on a printed circuit board**  
versus cooling air temperature  $\theta_A$ ,  
mains operation 40 to 60 Hz, natural air cooling



**Overcurrent characteristic curves (mean value)**  
for heat sink E1, cooling type (S),  $\theta_A = 45^\circ\text{C}$ ,  
mains operation 40 to 60 Hz. Parameters:  
basic load current  $I_{F(BL)}$ , current waveform



**Intermittent operation with basic load for heat sink E 1,**  
 cooling type (S),  $\theta_A = 25^\circ\text{C}$ , mains operation 40 to 60 Hz. Parameters:  
 basic load current  $I_{F(BL)}$ , cycle time SD, current waveform

